

**R E M A R K S**

Reconsideration of this application, as amended, is respectfully requested.

**RE: THE ALLOWABLE SUBJECT MATTER**

The Examiner's indication of the allowability of the subject matter of claims 9 and 10 is respectfully acknowledged.

Claim 9 has been amended so as to be rewritten in independent form to include all of the limitations of its parent claim 1 and intervening claim 2.

In addition, claims 9 and 10 have been amended to make some minor grammatical improvements and to correct some minor antecedent basis problems so as to put them in better form for issuance in a U.S. patent.

Clearly, no new matter has been added, and no new issues with respect to patentability have been raised.

Accordingly, it is respectfully submitted that amended independent claim 9 and claim 10 depending therefrom are now in condition for immediate allowance.

**RE: THE OTHER CLAIMS**

Claim 1 has been amended to incorporate the subject matter of claims 2, 3, 8 and 11 (which have been canceled).

In addition, claims 1, 4-7 and 12-15 have been amended to make some minor grammatical improvements and to correct some minor antecedent basis problems so as to put them in better form for issuance in a U.S. patent.

Still further, claims 4-7 and 11 have been amended to depend from claim 1.

Yet still further, new claim 29 has been added depending from claim 12 to recite the feature of the present invention whereby an encapsulating film is formed around the columnar electrode on the insulating film, as supported by the disclosure in the specification at page 8, line 25 to page 9, line 3.

And finally, non-elected claims 16-28 have been canceled, without prejudice.

No new matter has been added, and it is respectfully requested that the amendments to claims 1, 4-7 and 12-15 and the addition of claim 29 be approved and entered.

#### THE PRIOR ART REJECTION

Claims 1, 3, 5, 6 and 13 were rejected under 35 USC 102 as being anticipated by US Application Publication No. 2002/0093078 ("Paek"). This rejection, however, is respectfully traversed with respect to claim 1 as amended hereinabove.

According to the present invention as recited in claim 1, the semiconductor package comprises, in particular, a support

substrate which formed on the side of the first surface of the semiconductor substrate so as to support the semiconductor substrate. That is, the support substrate is formed on the side of the surface of the semiconductor substrate on which the device region is formed.

By contrast, it is respectfully submitted that according to Paek, the semiconductor die 310 is supported by the substrate 330 (not by the glass 350). And it is respectfully submitted that the substrate 330 of Paek is not on the "first" surface of the semiconductor substrate, but is instead provided on the "second" side, the side of the semiconductor substrate which is opposite to the light receiving surface 314.

In addition, it is respectfully pointed out that according to Paek the semiconductor die 310 includes a die conductive via 316 formed in the die via hole 315 formed therethrough. And it is respectfully submitted that this method of forming the die via hole directly through the semiconductor die is an inefficient process which requires an increased area of the semiconductor substrate.

By contrast, according to the present invention as recited in claim 1, the semiconductor package comprises, in particular, a connecting wire which is formed on a side of the first surface of the semiconductor substrate and which includes a first end electrically connected to the connecting pad and a second end

extending outside of the semiconductor substrate; an insulating film formed on the second surface of the semiconductor substrate and the connecting wire and having a hole at a position corresponding to the second end of the connecting wire an external electrode formed on the insulating film; and a distribution wire for electrically connecting the connecting wire and external electrode via the hole in the insulating film. With this structure, an electrical connection is enabled between the connecting pad and the external electrode without forming a hold through the semiconductor substrate.

Accordingly, it is respectfully submitted that amended independent claim 1, and amended claims 4-7 and 12-15 depending therefrom, all patentably distinguish over Paek, under 35 USC 102 as well as under 35 USC 103.

RE: KOUNO ET AL

Claims 1-8, 11, 12, 14 and 15 were rejected under 35 USC 102(e) as being anticipated by US Application Publication No. 2003/0230804 ("Kouno et al").

It is respectfully pointed out, however, that Kouno et al has a filing date of June 10, 2003, which is after the priority date of the present application of September 20, 2002. Thus, in order to remove Kouno et al as a reference, submitted herewith is an accurate English translation of Japanese Patent Application

No. 2002-274807, which is the priority document of the present application. The present claimed invention is fully supported by the disclosure in Japanese priority application No. 2002-274807.


Accordingly, it is respectfully submitted that the present claimed invention is entitled to the priority date of September 20, 2002, and it is respectfully submitted that Kouno et al is not a proper reference under 35 USC 102(e). Therefore, it is respectfully requested that the rejection under 35 USC 102 in view of Kouno et al be withdrawn.

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In view of the foregoing, entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned for prompt action.

Respectfully submitted,

  
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